Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1A**
2. **1B**
3. **1Y**
4. **2A**
5. **2B**
6. **2Y**
7. **GND**
8. **3Y**
9. **3A**
10. **3B**
11. **4Y**
12. **4A**
13. **4B**
14. **VCC**

**.024”**

**13 12 11 10 9**

**2 3 4 5**

**8**

**7**

**6**

**14**

**1**

**HC00X**

**MASK**

**REF**

**.024”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .0035” X .0035”**

**Backside Potential: VCC or FLOAT**

**Mask Ref: HC00**

**APPROVED BY: DK DIE SIZE .024” X .024” DATE: 7/18/22**

**MFG: SILICON SUPPLIES THICKNESS .014” P/N: 54HC00**

**DG 10.1.2**

#### Rev B, 7/19/02